

result of check to the electronic component mounting apparatus 300 in the latter stage.--

Please replace the Abstract of the Disclosure with the following revised abstract:

--This invention provides an electronic component mounting method capable of effectively utilizing a self-alignment effect even if a mounting interval of electronic components is small. This method includes the steps of detecting a printing position of a solder paste on the circuit board and mounting an electronic component. ~~This invention further provides apparatus, devices, and system using the method.~~ When a solder paste on a circuit board having a land formed thereon is printed and an electronic component is mounted, the printing position of the solder paste of the circuit board is detected by a printing position detecting device included in an inspecting apparatus. Then, the electronic component is mounted by using the detected printing position of the solder paste as a reference by an electronic component mounting apparatus.--

Attachment: Replacement Sheet (clean copy of Abstract)